

a plurality of wiring layers formed so as to correspond to a predetermined circuit pattern, said wiring layers being laminated at least on said first surface and said second surface of said insulating layer;

a via formed on said insulating layer, said via having one end opened on said first surface of said insulating layer and the other end closed by said wiring layer laminated on a part of said insulating layer other than said first surface;

Plating
a first plating layer, said first plating layer continuously covering said inner surface of said via, said wiring layer exposed within said via and that portion of the wiring layer which is formed on said first surface and which faces one end of said via; and

a second plating layer, said second plating layer being laminated on said first plating layer, electrically connecting said wiring layer formed on said first surface and said wiring layer laminated on the part of said insulating layer other than said first surface by cooperating with said first plating layer.

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5. (Amended) The printed wiring board according to claim 1, wherein said insulating layer and said wiring layers form a laminate, and one of said wiring layers is formed inside said insulating layer, is exposed within said via, and is covered by said first plating layer.

REMARKS

In response to the Restriction Requirement of April 30, 2002, Applicant elects invention I and Claims 1-6 for further prosecution on the merits. Further, the election requirement is now moot in view of the presently submitted claim amendments. That is, Applicant respectfully believes that each of currently pending Claims 1, 2, 3, and 5 read on a single species.